



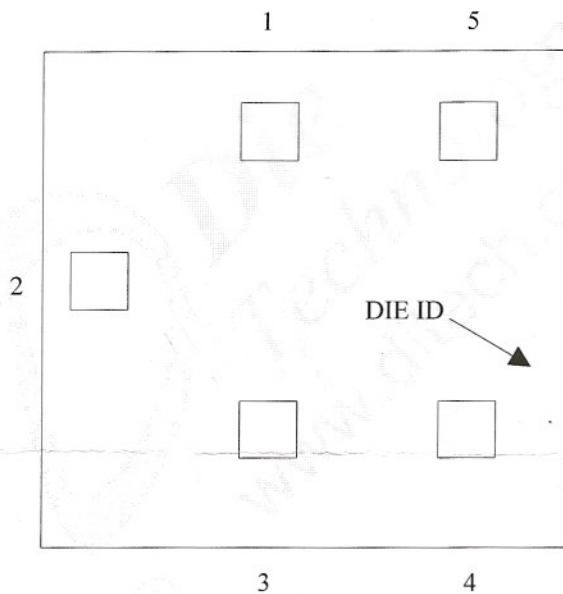
# Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

### PAD FUNCTIONS

- 1 V<sub>DD</sub>
- 2 GND
- 3 TTL IN
- 4 OUT +
- 5 OUT -



The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

**Note: 1 mil = 0.001inch**

<u>APPROVED</u>  NM	<b>DS90LV011A MDC</b>  <b>NATIONAL SEMICONDUCTOR</b>	<u>DIE INFORMATION</u>
DATE: 24/01/2008		DIMENSIONS (Mils): 35 x 33 x 10 BOND PADS (Mils): 4 x 4 MASK REF: B DIE ID: DS90LV011AB BACK POTENTIAL: GND
<u>SERIAL NUMBER</u> 008789		<u>METALLISATION</u>
		TOP: Al BACK: Si